# AMPAK Technology, Inc.

## **AP615JC Brief**

An Advanced Module Packaging and Testing Solution Provider.

#### **Features**

## **System**

- Chipset: STM32WLE5xx
- High performance ARM® Cortex® -M4 32-bit

RISC core operating up to 48 MHz frequency

• Embedded memories (up to 256 Kbytes of

Flash memory and 64 Kbytes of RAM)

- Hardware encryption AES 256-bit
- True random number generator (RNG)
- CRC calculation unit
- Unique device identifier (64-bit UID compliant

with IEEE 802-2001 standard)

- 96-bit unique die identifier
- Hardware public key accelerator (PKA)
- 1.8 V to 3.6 V power supply
- -40 °C to +85 °C temperature range

### **Clock Source**

32 MHz TCXO

32 kHz XTAL for RTC

## **System peripherals**

- 2 DMA, 2 USART, 1 LPUART, 2 SPI, 3 I2C
- RTC wakeup counter, SysTick, Watchdog
- Channel Timer

#### **Radio**

- LoRa Modem
- +22 dBm max. RF output vs. V supply
- Programmable bit rate up to 300 kbps
- High sensitivity: down to -136 dBm for LoRa

@125kHz, SF12 and -122dBm for 2-FSK @1.2kbps

- Excellent blocking immunity
- Automatic RF Sense and CAD with ultra-fast

**AFC** 

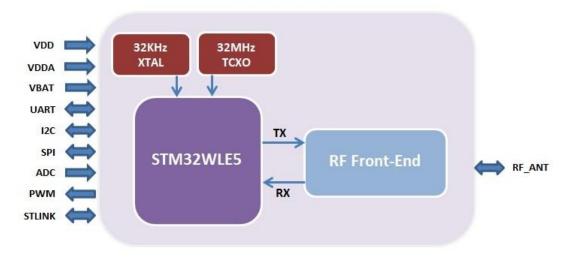
• Supports FSK, GFSK, MSK, GMSK, BPSK,

LoRa modulation

- Epoxy molding finished module in LGA type
- Small footprint: 11 mm x 11 mm x 1.4 mm

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# **Block Diagram**



Technical Specification				
Model Name	EZ55WL			
Product Description	LoRa Wireless Communication Module			
Package	LGA type			
Host Interface	UART			
Dimension	11 mm x 11 mm x 1.4 mm			
	Operation Conditions			
Operating Voltage	■ 3.3V			
Temperature	■ Storage: -50°C ~+105°C			
	■ Operating: -40°C ~+85°C			
Humidity	■ Operating: 10 ~ 95% (Non-Condensing)			
	■ Storage: 5 ~ 95% (Non-Condensing)			
	Electrical Specifications			
Frequency	779-928 MHz ISM frequency band			
Band Width	LoRa® Rx/Tx, BW = 7.8 - 500 kHz			
Bit rate	LoRa: BR = $0.013 - 17.4 \text{ kb/s}$ , (G)FSK: BR = $0.6 - 300 \text{ kb/s}$			
SF	LoRa: SF5 to SF12,			
Tx Power	+22dBm max.			
Sensitivity	Down to -136dBm			

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PIN Definition				
Pin No.	Pin Name	Pin No.	Pin Name	
1	GND	31	PA8	
2	PA13(SWDIO)	32	PA9	
3	PA14(SWCLK)	33	NRST	
4	PA15	34	BOOT0	
5	PB5	35	GND	
6	PB4	36	GND	
7	PB3	37	RF_ANT	
8	VREF+	38	GND	
9	VDDA	39	GND	
10	VFBSMPS	40	GND	
11	GND	41	GND	
12	VDD	42	GND	
13	VDDSMPS	43	GND	
14	VLXSMPS	44	GND	
15	PB6	45	PB9	
16	PB7	46	PB10	
17	PB8	47	PB11	
18	PC0	48	PB12	
19	PC1	49	PB13	
20	PC2	50	PB14	
21	PC3	51	PB15	
22	PC6	52	GND	
23	PA0	53	VDDPA	
24	PA1	54	PB1	
25	PA2	55	PB2	
26	PA3	56	VBAT	
27	PA4	57	PA10	
28	PA5	58	PA11	
29	PA6	59	PA12	
30	PA7	60	PC13	
61~65	GND			

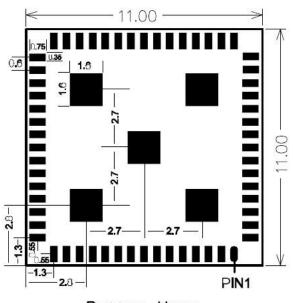
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#### **Mechanical Dimension**

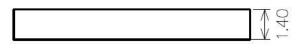
Unit: mm

Unit: mm





Bottom View



Side View